

**Thermal resistance**

| Parameter | Symbol | Min. | Typ. | Max. | Unit |
|--|------------|------|------|------|------|
| Thermal resistance, junction - ambient | R_{thJA} | - | - | 150 | C/W |
| Soldering temperature, wavesoldering for 10s | T_{sold} | - | - | 265 | C |

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|--------------------------------|--------------|-----------------------------------|------|------|------|------|
| Drain-Source Breakdown Voltage | BV_{DSS} | $V_{GS} = 0V, I_D = 250\mu A$ | 60 | | | V |
| Gate Threshold Voltage | $V_{GS(TH)}$ | $V_{GS} = V_{DS}, I_D = 250\mu A$ | 1.5 | | 2.5 | V |

Drain-Source Leakage Current I_D

Fig.1 Gate-Charge Characteristics

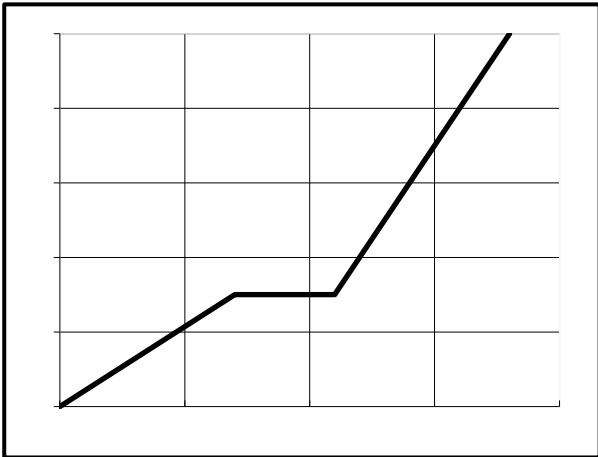


Fig.2 Capacitance Characteristics

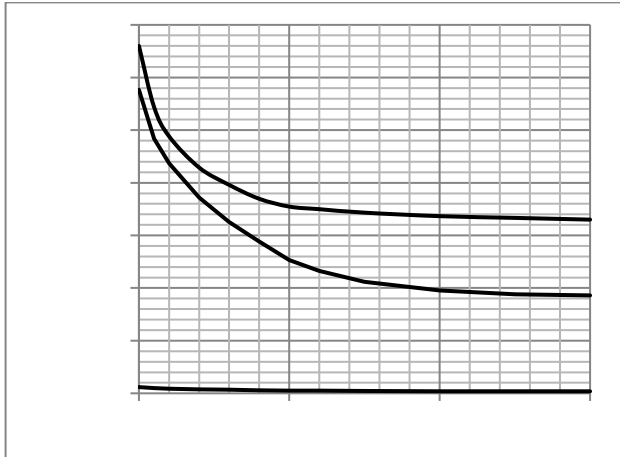


Fig.3 Power Dissipation

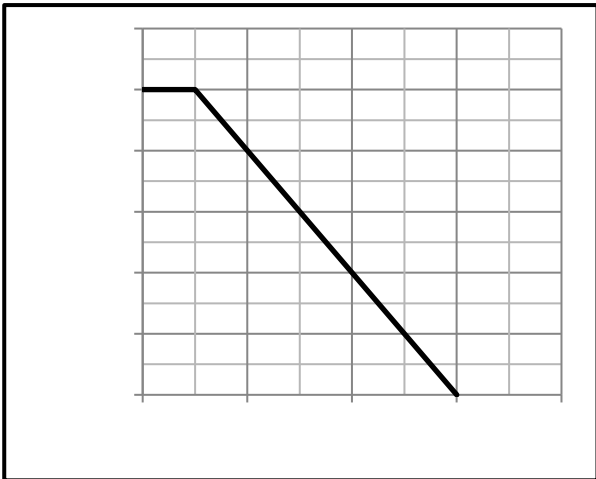


Fig.4 Typical output Characteristics

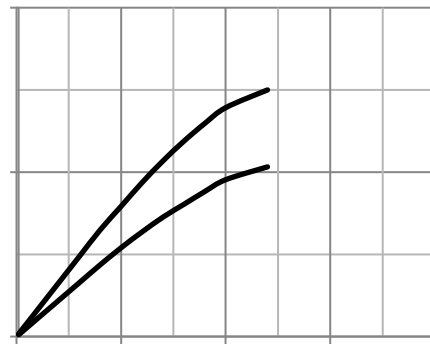


Fig.5 Threshold Voltage V.S Junction Temperature

Fig.6 Resistance V.S Drain Current

Fig.13 Switching Time Measurement Circuit

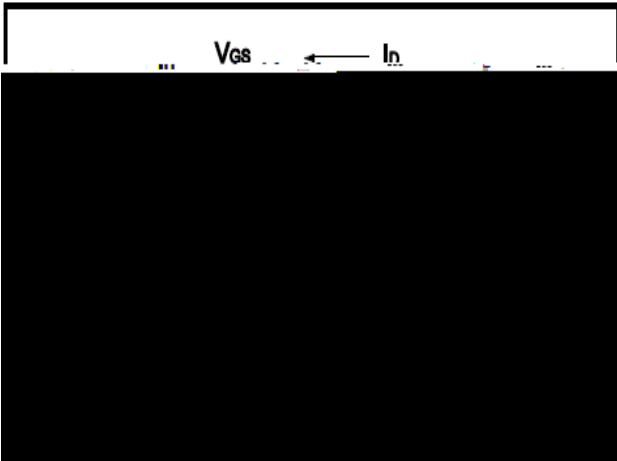


Fig.14 Gate Charge Waveform

